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SEMICONDUCTOR WAFER DIVIDING METHOD

Abstract of the Disclosure

A semiconductor wafer dividing method for dividing a semiconductor wafer, on whose face side many rectangular areas are demarcated by streets arranged in a lattice fashion, along the streets to convert each of the many rectangular areas into a semiconductor chip. In this method, a resist is formed on the face side of the semiconductor wafer. Then, the resist is physically removed in areas extending along the streets. Then, an etching process is applied to the semiconductor wafer to etch the semiconductor wafer along the streets.

Figure 4

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